IPC-6012E

2020 - March

Qualification and Performance Specification for Rigid Printed Boards

Supersedes IPC-6012D
September 2015

An international standard developed by IPC

Association Connecting Electronics Industries

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- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

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- Increase time-to-market
- Keep people out
- Increase cycle time
- Tell you how to make something
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Qualification and Performance Specification for Rigid Printed Boards

Developed by the Rigid Printed Board Performance Specifications Task Group (D-33a) of the Rigid Printed Board Committee (D-30) of IPC

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IPC-6012D - September 2015
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Users of this publication are encouraged to participate in the development of future revisions.

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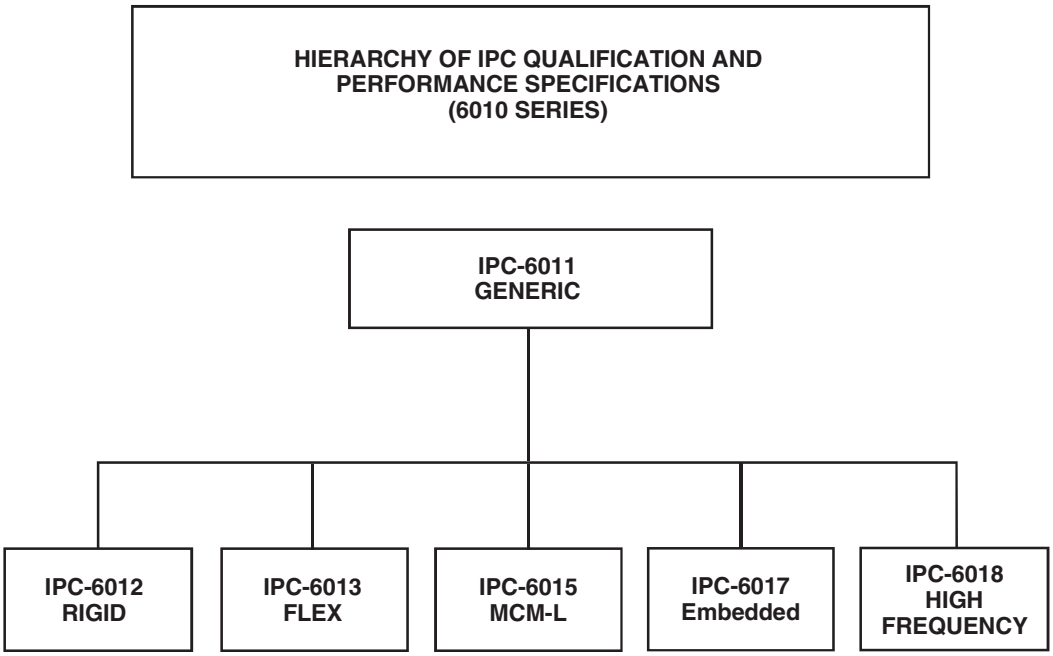

FOREWORD

This specification is intended to provide information on the detailed performance criteria of rigid printed boards. It supersedes IPC-6012B and was developed as a revision to those documents. The information contained herein is also intended to supplement the generic requirements identified in IPC-6011. When used together, these documents should lead both manufacturer and customer to consistent terms of acceptability.

IPC's documentation strategy is to provide distinct documents that focus on specific aspects of electronic packaging issues. In this regard, document sets are used to provide the total information related to a particular electronic packaging topic. A document set is identified by a four digit number that ends in zero (0) (i.e., IPC-6010).

Included in the set is the generic information, which is contained in the first document of the set. The generic specification is supplemented by one or multiple performance documents, each of which provide a specific focus on one aspect of the topic or the technology selected.

Failure to have all information available prior to building a board may result in a conflict in terms of acceptability.

As technology changes, a performance specification will be updated, or new focus specifications will be added to the document set. The IPC invites input on the effectiveness of the documentation and encourages user response through completion of "Suggestions for Improvement" forms located at the end of each document.

Acknowledgment

Any document involving a complex technology draws material from a vast number of sources across many continents. While the principal members of the Rigid Printed Board Performance Specifications Task Group (D-33a) of the Rigid Printed Board Committee (D-30) are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of the IPC extend their gratitude.

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